# 深圳市诚皓光电有限公司

# Shenzhen ChengHao Optoelectronic Co., Ltd.

# **SPECIFICATION**

Product Model: CH240QV23A-T

Designed by	R&D Checked by	Quality Department by	Approved by

# **Approval by Customer**

OK	
NG, Problem survey:	
	Approved By

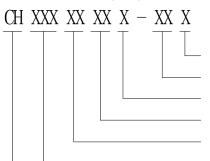
# **Revision Record**

REV NO.	REV DATE	CONTENTS	Note
V0	2019-11-17	NEW ISSUE	

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## 1. Numbering System



- 7. Extended version: A~Z

- 6. Touch panel or other materials, e.g. T:RTP, CT:CTP, L:LENS

5. Extended version: A<sup>2</sup>Z4. Serial number: 01<sup>99</sup>

— 3. Resolution, e.g. QV:QVGA 240\*320; WV:WVGA 480\*800; FH:FHD 1080\*1920

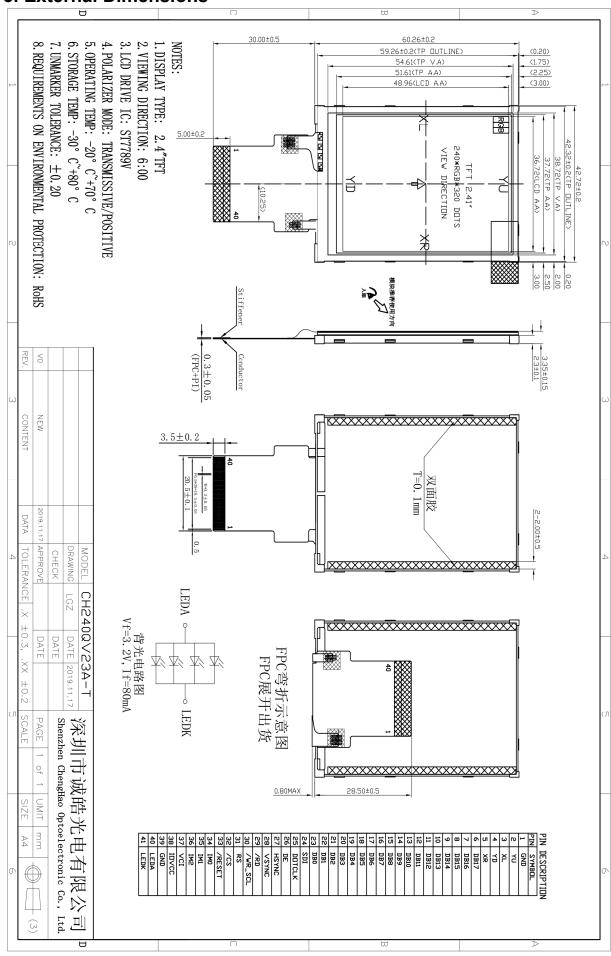
- 2. Size, e. g. 2. 4": 240; 7":700

---- 1. Shenzhen ChengHao Optoelectronic Co., Ltd.

### 2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.4"TFT	
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	
Viewing Direction	6 o'clock	
Gray Scale Inversion Direction	12 o'clock	
Driver IC	ST7789V	
Module size	42.72(W)×60.26(H)×2.45(T)	mm
Active area	36.72(W)×48.96(H)	mm
Dot pitch	0.153 (W)×0.153 (H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/9-/16-/18-bit 8080 system interface 6-/16-/18-bit RGB interface	
Operating temperature	-20 ~ +70	${\mathfrak C}$
Storage temperature	-30 ~ +80	${\mathbb C}$
Back Light	4 White LED In Parallel	
Weight	TBD	g

#### 3. External Dimensions



4. Interface Description

<u>4. I</u>	nterrace	Description							
Pin	Symbol	Description.							
1	XR								
2	YD	TOUCH PIN.							
3	XL	1000111 114.							
4	YU								
5	DB17								
6	DB16								
7	DB15								
8	DB14								
9	DB13	19 bit parallal bi directional data bus for MDLL I system:							
10	DB12	18-bit parallel bi-directional data bus for MPU- I system: 8-bit I/F: DB[7:0] is used.							
11	DB11	9-bit I/F: DB[8:0] is used.							
12	DB10	16-bit I/F: DB[15:0] is used.							
13	DB9	18-bit I/F: DB[17:0] is used.							
14	DB8	18-bit input data bus for RGB I/F.							
15	DB7	6-bit/pixel: DB[5:0] is used;							
16	DB6	16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0];							
17	DB5	18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0];							
18	DB4	Connect unused pins to GND.							
19	DB3								
20	DB2								
21	DB1								
22	DB0								
23	SDI	Serial input signal in SPI I/F.							
24	DOTCLK	Pixel clock signal in RGB I/F.							
25	DE	Data enable signal in RGB I/F mode							
26	HSYNC	Horizontal sync signal in RGB I/F.							
27	VSYNC	Vertical sync signal in RGB I/F.							
28	/RD	Reads strobe signal to write data when /RD is "Low" in MPU interface.							
29	/WR_RS	MCU: Serves as a write signal and writes data at the rising edge. 4-line SPI: Serves as command or parameter select.							
30	RS_SCL	Display data / command selection in 80-series MPU I/F. RS = "0" : Command RS = "1" : Display data. SPI: This pin is used serial interface clock in SPI.							
31	/CS	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.							
32	/RESET	Reset input pin, Active "L".							
33	IM0	System interface Mode    IM2   IM1   IM0   Interface mode   DB Pin							
		0         0         0         i80-system 8-bit interface I         DB[7:0]           0         0         1         i80-system 16-bit interface I         DB[15:0]							
34	IM1	0 1 0 i80-system 9-bit interface I DB[8:0]							
		0 1 1 i80-system 18-bit interface I DB[17:0]							
35	IM2	1         0         1         3-wires_9-bit SPI I         /CS,SDI,SCL           1         1         0         4-wires_8-bit SPI I         /CS,RS,SDI,SCL							

36	VCI	System power supply.
37	IOVCC	I/O power supply.
38	GND	Power ground
39	LEDA1	LED backlight (Anode).
40	LEDK	LED backlight (Cathode).

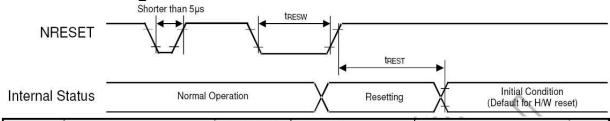
**5. Absolute Maximum Ratings** 

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

### 6. DC Characteristics

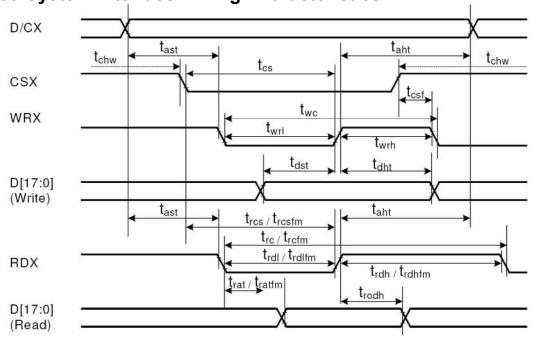
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	٧	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	٧	-
Input High Voltage	V <sub>IH</sub>	0.7IOVCC	1	IOVCC	V	Digital input pins
Input Low Voltage	V <sub>IL</sub>	GND	-	0.3IOVCC	٧	Digital input pins
Output High Voltage	V <sub>OH</sub>	0.8IOVCC	1	IOVCC	V	Digital output pins
Output Low Voltage	V <sub>OL</sub>	GND	1	0.2IOVCC	V	Digital output pins
I/O Leak Current	lu	-0.1	1	0.1	uA	-

# 7. Timing Characteristics7.1 Reset Timing Characteristics



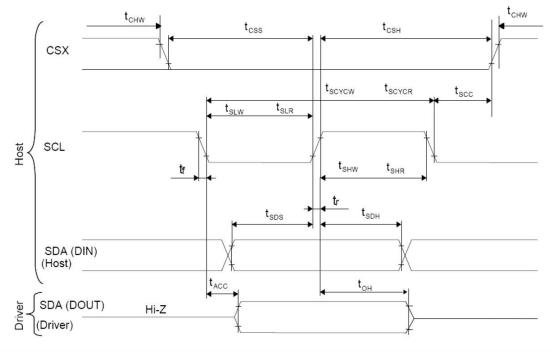
Symbol	Darameter	Parameter Related Spec.				Note	Unit
Syllibol	Faranietei	Pins	Min.	Тур.	Max.	Note	Oilit
tRESW	Reset low pulse width <sup>(1)</sup>	NRESET	10		-11	·	μs
tREST	Reset complete time <sup>(2)</sup>	-	5	<	3	When reset applied during SLPIN mode	ms
INEST	neset complete time	n <del>-</del> 1	120	0	),	When reset applied during SLPOUT mode	ms

# 7.2 i80-System Interface Timing Characteristics



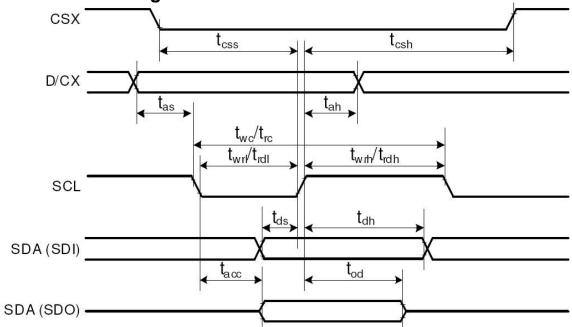
Signal	Symbo I	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
DCX	taht	Address hold time (Write/Read)	0		ns	
	tchw	CSX "H" pulse width	0		ns	
	tcs	Chip Select setup time (Write)	15	(2 <b>%</b> )	ns	
CSX	trcs	Chip Select setup time (Read ID)	45		ns	
	trcsfm	Chip Select setup time (Read FM)	355		ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	· ·	ns	
WRX	twrh	Write Control pulse H duration	15		ns	
	twrl	Write Control pulse L duration	15		ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90		ns	
	trdlfm	Read Control L duration (FM)	355	3.00	ns	
	trc	Read cycle (ID)	160		ns	
RDX (ID)	trdh	Read Control pulse H duration	90		ns	
	trdl	Read Control pulse L duration	45		ns	
D[17:0], D[17:10]&D[8:1],	tdst	Write data setup time	10		ns	
	tdht	Write data hold time	10		ns	
	trat	Read access time	650	40	ns	For maximum CL=30pF For minimum CL=8pF
D[17:10], D[17:9]	tratfm	Read access time	828	340	ns	Tot minimum oc=opr
0[17.0]	trod	Read output disable time	20	80	ns	

# 7.3 3-line SPI Timing Characteristics



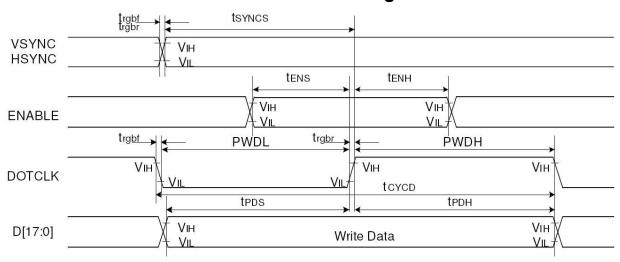
Signal	Symbol	Parameter	min	max	Unit	Description
	tscycw	Serial Clock Cycle (Write)	100	2 <u>4</u> 8	ns	
	tshw	SCL "H" Pulse Width (Write)	40		ns	
SCL	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
SOL	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	400	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI	tsds	Data setup time (Write)	30	1=0	ns	
(Input)	tsdh	Data hold time (Write)	30	140	ns	
SDA / SDO	tacc	Access time (Read)	10	2400	ns	
(Output)	toh	Output disable time (Read)	10	50	ns	
	tscc	SCL-CSX	20		ns	
007	tchw	CSX "H" Pulse Width	40		ns	
CSX	tcss	CSV SCI Time	60	40	ns	
	tcsh	CSX-SCL Time	65	17.0	ns	

# 7.4 4-line SPI Timing Characteristics



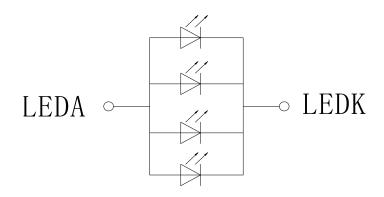
Signal	Symbol	Parameter	min	max	Unit	Description
CCV	tcss	Chip select time (Write)	40	u	ns	
CSX tcsh		Chip select hold time (Read)	40	-	ns	
	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
SCL	twrl	SCL "L" pulse width (Write)	40	2	ns	
SCL	trc	Serial clock cycle (Read)	150	ā	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	· ·		
D/CX	tah	D/CX hold time (Write / Read)	10	5		
SDA / SDI	tds	Data setup time (Write)	30	-	ns	
(Input)	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO tacc		Access time (Read)	10	u	ns	For maximum CL=30pF
(Output)	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

# 7.5 Parallel 18/16/6-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	400	ns	
HSYNC	t <sub>SYNCH</sub>	VSYNC/HSYNC hold time	15	-	ns	
DE	t <sub>ENS</sub>	DE setup time	15	48	ns	
DE	t <sub>ENH</sub>	DE hold time	15		ns	
D[17:0]	t <sub>POS</sub>	Data setup time	15	===	ns	18/16-bit bus RGB
D[17.0]	t <sub>PDH</sub>	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	127	ns	
DOTCLK	PWDL	DOTCLK low-level period	15	-	ns	
DOTOLK	tcycd	DOTCLK cycle time	100	-	ns	
2	t <sub>rgbr</sub> , t <sub>rgbf</sub>	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	120	ns	
HSYNC	t <sub>SYNCH</sub>	VSYNC/HSYNC hold time	15	.=x	ns	
DE	t <sub>ENS</sub>	DE setup time	15		ns	
DE	t <sub>ENH</sub>	DE hold time	15	.70	ns	
D[17:0]	t <sub>POS</sub>	Data setup time	15	-	ns	6-bit bus RGB
D[17:0]	t <sub>PDH</sub>	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level pulse period	15	40	ns	
DOTCLK	PWDL	DOTCLK low-level pulse period	15	-	ns	
DOTCER	tcycD	DOTCLK cycle time	100		ns	
	t <sub>rgbr</sub> , t <sub>rgbf</sub>	DOTCLK,HSYNC,VSYNC rise/fall time	5=0	15	ns	

# 8. Backlight Charasterics



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.4	V	If=80mA
Supply Current	lf	-	80	-	mA	-
Luminous Intensity for LCM	-	250	300	-	Cd/m <sup>2</sup>	If=80mA
Uniformity for LCM	-	80	-	-	%	If=80mA
Life Time	-	20000	-	-	Hr	If=80mA
Backlight Color				White		

# 9. Optical Characteristics

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Transmittance (without Polarizer)		T(%)	1		(14.4)		3	
Contrast Ratio		CR	⊖=0	400	500	% <u></u>	=	(1)(2)
	Rising	T <sub>R</sub>	Normal viewing	<b>*</b> —	4	8		
Response time	Falling	T <sub>F</sub>	angle —	_	12	24	msec	(1)(3)
Color gamut		S(%)			60	3	%	
	White	W <sub>x</sub>		0.283	0.303	0.323		
1		Wy		0.305	0.325	0.345		
4	Red	Rx		0.606	0.626	0.646		
Color		Ry		0.314	0.334	0.354		(1)(4)
chromaticity	Green	Gx		0.257	0.277	0.297		CF glass
(CIE1931)		Gy		0.529	0.549	0.569		(C-light)
\$	Division	Вх		0.122	0.142	0.162		
,	Blue	Ву		0.102	0.122	0.142		3
,	1.1	θL		35	45	_	*	
	Hor.	θR	OD: 10	35	45	_		
Viewing angle		θυ	CR>10	35	45	Ī		
	Ver.	θρ		10	20	<u> </u>		ū

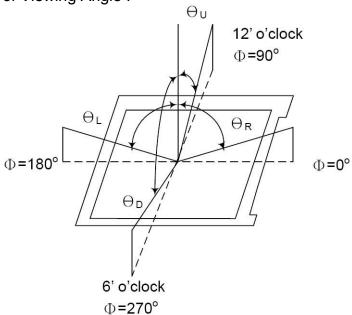
#### **Measuring Condition:**

Dark room, 25±2°C, 15min. warm-up time.

#### **Measuring Equipment**

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1) Definition of Viewing Angle:

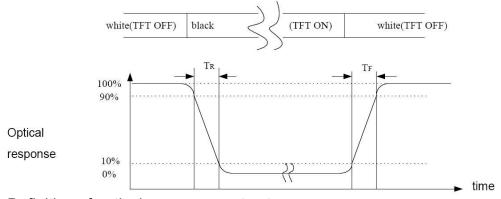


Note (2) Definition of Contrast Ratio(CR):

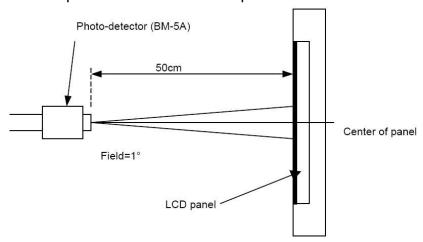
Measured at the center point of panel

CR = Luminance with all pixels white / Luminance with all pixels black

Note (3) Definition of Response Time: Sum of TR and TF



Note (4) Definition of optical measurement setup



10. Reliability Test Conditions And Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
1	High Temperature Storage	80℃±2℃×96Hours	
2	Low Temperature Storage	-30℃±2℃×96Hours	
3	High Temperature Operating	70℃±2℃×96Hours	Inspection after 2~4hours
4	Low Temperature Operating	-20℃±2℃×96Hours	storage at room temperature,the samples should be free from
5	Temperature Cycle(Storage)	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	defects: 1,Air bublle in the LCD. 2,Sealleak. 3,Non-display. 4,Missing segments.
6	Damp Proof Test (Storage)	50℃±5℃×90%RH×96Hours	5,Glass crack. 6,Current IDD is twice higher than initial value.
7	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7,The surface shall be free from damage. 8,The electric charateristic requirements shall be
8	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
9	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

#### REMARK:

- 1,The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test,Pure water(Resistance  $> 10M\Omega$ )should be used.
- 4,In case of malfunction defect caused by ESD damage,if it would be recovered to normal state after resetting,it would be judge as a good part.
- 5,EL evaluation should be excepted from reliability test with humidity and temperature:Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

#### 11. Inspection Standard

This standard apply to C-STN/TFT module

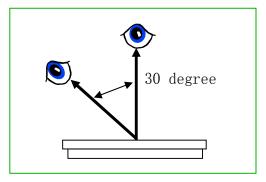
#### 1. Spot check plan:

According to spot check level II, MIL-STD-105D Level II, the rank of accept or reject is below:

3A 级、2A 级: major non-conformance: AQL 0.25 minor non-conformance: AQL 0.4

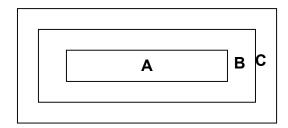
A 级: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

#### 2. Inspection condition:



Under daylight lamp 20  $\sim$  40W, product distance inspector'eye 30cm,incline degree 30°.

#### 3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assemby

Remark :non-conformance at area C,but is OK that isn't influence raliability of product & assembly by customer.

4. Inspection standard
4.1 Major non-conformance

NO.	Item Inspection standard		Rate
4.1.1	Function non-confor mance	<ol> <li>No display, display abnormaly</li> <li>Miss line, short</li> <li>B/L no function or function abnormaly</li> <li>TP no function</li> </ol>	major
4.1.2	miss	No matter miss what component	
4.1.3	Out of size	Module dimension out of spec	

# 4.2 Appearance non-conformance

NO.	Item			Insp	ection st	anda	ırd		Rate		
			dot non-conformance define $\Phi$ $\Phi = \frac{(x+y)}{2}$								
		A grade									
		a	rea		Most app	rove	q'ty				
	Black or white	size (mm)	<b>)</b>	Α	В	3	С				
4.2.1	spot	Ф≤0.1	0		ignore				Minor		
	(power on)	0.10<Φ≤	0.15		3						
		0.15<Φ≤	0.20		2		ignore	e			
		0.20<Φ≤0.25			1						
		0.25<	Ф		0						
		Most approve 4 damages, dot to dot ≥10mm									
		A grade									
		Size(mm)			Most approve q'			q'ty			
		L(length)	W(w	ridth)	Α		В	С			
	Black or	ignore	W≤0.03		ignore						
4.2.2	white line (power on)	L≤5.0	0.03< W≤0.05		2				Minor		
		L≤3.0		05< 0.07	1 Treat with dot non-conformance			ignore			
			0.07	<b>7</b> <w< td=""><td></td><td></td></w<>							
		Most approve 3 damages, line to line ≥10mm									
4.2.3	Polarizer position		polarizer attach meet drawing, disallow out of LCD.						Minor		

4.2.4	LCD non-conf ormance	X  ≤3 Crash d  (ii) commonly sur  X  ≤2.0  (iii) crack Disallow exter	isallow extend to ITO face scathe  Y <frame edge<="" th=""/> <th>Z ignore</th> <th>Minor</th>	Z ignore	Minor		
4.2.5	Contrast voltage warp	VOP/VIcd voltage	Minor				
4.2.6	color	Color & luminance of module scope reference spec Mi					
4.2.7	Cross talk	Reference confirm	Minor				

#### 12. Handling Precautions

#### 12.1 Mounting method

The LCD panel of CH LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

#### 12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly

- İsopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl), Salfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Salfur (S) from customer, Responsibility is on customer.

#### 12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

#### 12.4 packing

- Module employ LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

#### 12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

#### 12.6 storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.

[It is recommended to store them as they have been contained in the inner container at the time of delivery from us

#### 12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

#### 13. Precaution For Use

#### 13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

#### 13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to CH LCD, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

#### 14. Packing Method

